BT169W Series

Thyristor logic level

GENERAL DESCRIPTION

Passivated, sensitive gate thyristor in a plastic envelope, suitable for surface mounting, intended for use in general purpose switching and phase control applications. This device is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

PINNING - SOT223

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	MAX.	UNIT
V _{drm} , V _{rrm}	BT169 Repetitive peak off-state voltages	BW 200	DW 400	EW 500	GW 600	V
I _{T(AV)}	Average on-state current	0.5	0.5	0.5	0.5	A
I _{T(RMS)} I _{TSM}	RMS on-state current Non-repetitive peak on-state current	0.8 8	0.8 8	0.8 8	0.8 8	A A

PIN CONFIGURATION

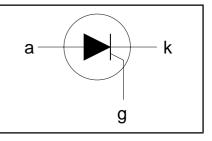
1

4

2

3

SYMBOL



PINDESCRIPTION1cathode2anode3gatetabanode

LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MA	AX.		UNIT
V _{drm} , V _{rrm}	Repetitive peak off-state voltages		-	B 200 ¹	D 400 ¹	E 500 ¹	G 600 ¹	V
I _{T(AV)}	Average on-state current	half sine wave; T₅₅ ≤ 112 °C	-		0.	63		А
I _{T(RMS)} I _{TSM}	RMS on-state current Non-repetitive peak on-state current	all conduction angles half sine wave; $T_i = 25 \degree C$ prior to surge	-			1		A
		t = 10 ms t = 8.3 ms	-		8	8 9		A A
l²t dl _⊤ /dt	I ² t for fusing Repetitive rate of rise of on-state current after	t = 10 ms $I_{TM} = 2 \text{ A}; I_G = 10 \text{ mA};$ $dI_G/dt = 100 \text{ mA/}\mu\text{s}$	-			32 50		A A²s A/µs
$\begin{matrix} I_{GM} \\ V_{GM} \\ V_{RGM} \\ P_{GM} \\ P_{G(AV)} \\ T_{stg} \\ T_{j} \end{matrix}$	triggering Peak gate current Peak gate voltage Peak reverse gate voltage Peak gate power Average gate power Storage temperature	over any 20 ms period	- - - - -40		0 1	1 5 2 .1 50		°°°° °°° A < <
T _j	Operating junction temperature		-		1:	25		°C

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 $A/\mu s$.

Thyristor	BT169W Series
logic level	

THERMAL RESISTANCES

SYMBOL	YMBOL PARAMETER CONDITIONS		MIN.	TYP.	MAX.	UNIT
R_{thj-sp}	Thermal resistance junction to solder point		-	-	15	K/W
R _{th j-a}	Thermal resistance	pcb mounted, minimum footprint pcb mounted; pad area as in fig:14	-	156 70	-	K/W K/W

STATIC CHARACTERISTICS

 $T_j = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_{D} = 12 \text{ V}; \text{ I}_{T} = 10 \text{ mA}; \text{ gate open circuit}$	-	50	200	μA
l I _L	Latching current	$V_{\rm D} = 12 \text{ V}; \text{ I}_{\rm GT} = 0.5 \text{ mA}; \text{ R}_{\rm GK} = 1 \text{ k}\Omega$	-	2	6	mA
I _H	Holding current	$V_{\rm D} = 12 \text{ V}; \text{ I}_{\rm GT} = 0.5 \text{ mA}; \text{ R}_{\rm GK} = 1 \text{ k}\Omega$	-	2	5	mA
İ Ϋ _τ	On-state voltage	$I_T = 2 A$	-	1.35	1.5	V
V _{GT}	Gate trigger voltage	$\dot{V}_{\rm D}$ = 12 V; I _T = 10 mA; gate open circuit	-	0.5	0.8	V
		$V_D = V_{DRM(max)}$; $I_T = 10 \text{ mA}$; $T_j = 125 \text{ °C}$; gate open circuit	0.2	0.3	-	V
I _D , I _R	Off-state leakage current	$\breve{V}_{D} = V'_{DRM(max)}; V_{R} = V_{RRM(max)}; T_{i} = 125 \text{°C};$	-	0.05	0.1	mA
1		$R_{GK} = 1 k\Omega$				

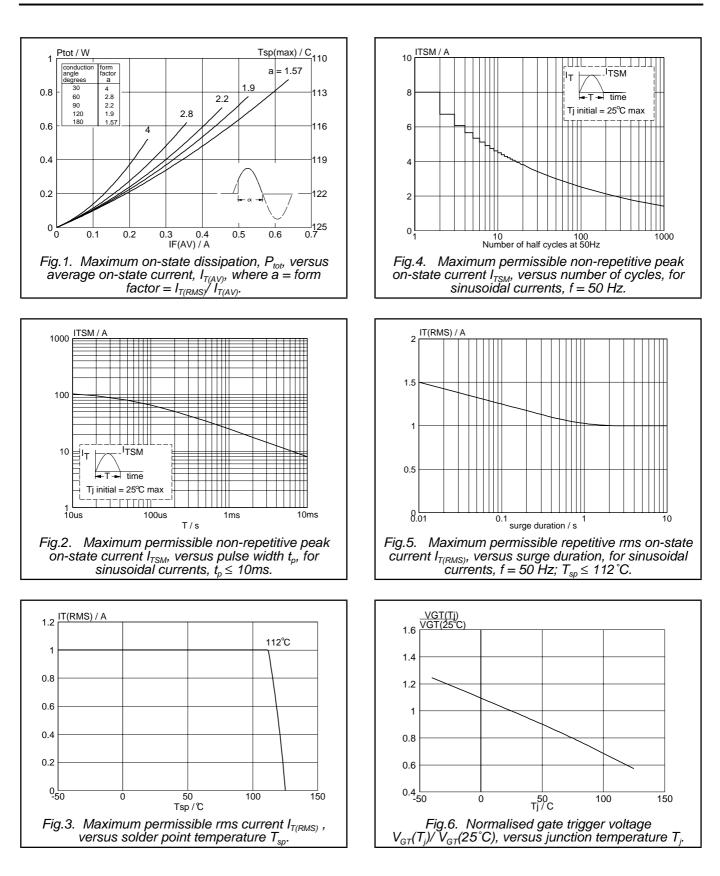
DYNAMIC CHARACTERISTICS

 $T_j = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	V_{DM} =67% $V_{DRM(max)}$; T _j = 125 °C; exponential waveform; R _{GK} = 1k Ω	500	800	-	V/µs
t _{gt}	Gate controlled turn-on time	$I_{TM} = 2 \text{ A}; V_D = V_{DRM(max)}; I_G = 10 \text{ mA};$ $dI_C/dt = 0.1 \text{ A/us}$	-	2	-	μs
t _q	Circuit commutated turn-off time		-	100	-	μs

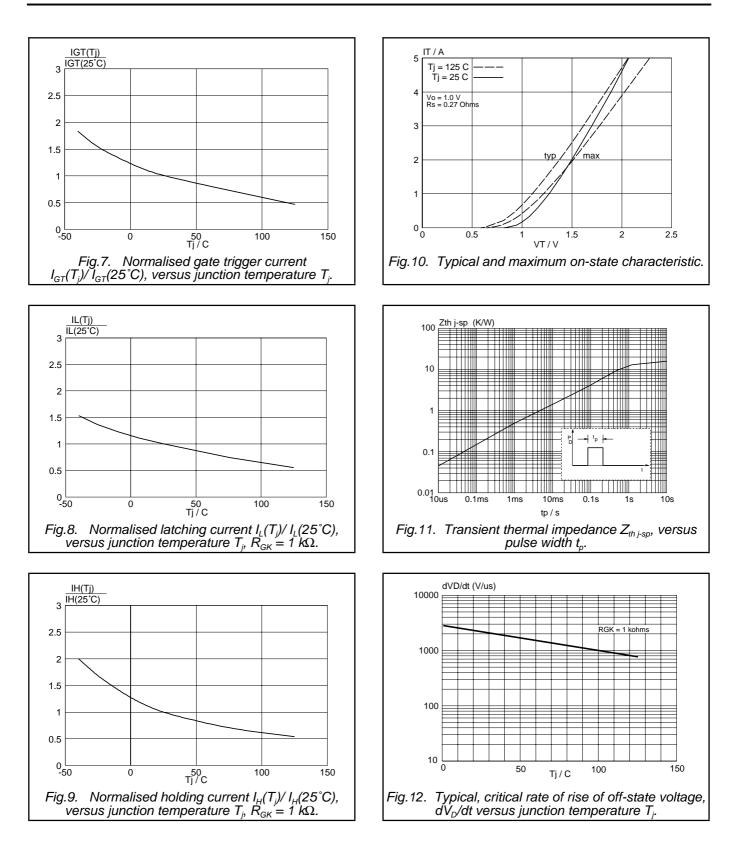
BT169W Series

Thyristor logic level



BT169W Series

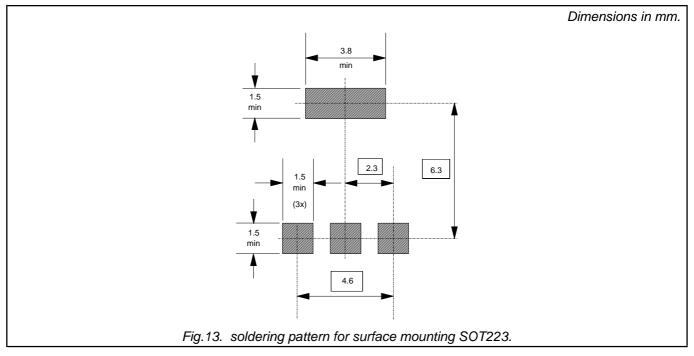
Thyristor logic level



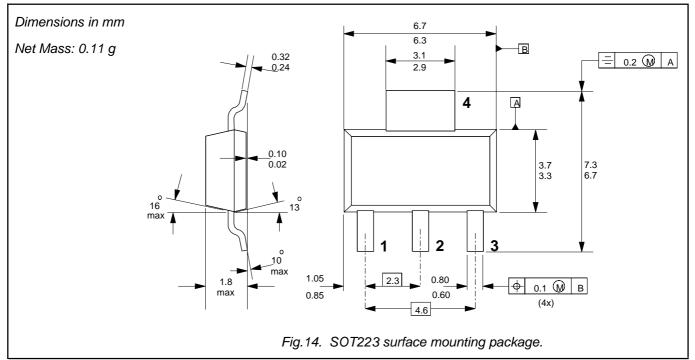
Thyristor logic level

BT169W Series

MOUNTING INSTRUCTIONS



MECHANICAL DATA



Notes

1. For further information, refer to Philips publication SC18 " SMD Footprint Design and Soldering Guidelines". Order code: 9397 750 00505. 2. Epoxy meets UL94 V0 at 1/8".

Thyristor logic level

BT169W Series

DEFINITIONS

DATA SHEET STATUS					
DATA SHEET STATUS ²	PRODUCT STATUS ³	DEFINITIONS			
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice			
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product			
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A			

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

© Philips Electronics N.V. 2001

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

² Please consult the most recently issued datasheet before initiating or completing a design.

³ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.